

2020 Q1 Results Announcement

22 Apr 2020

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Awards & Accolades

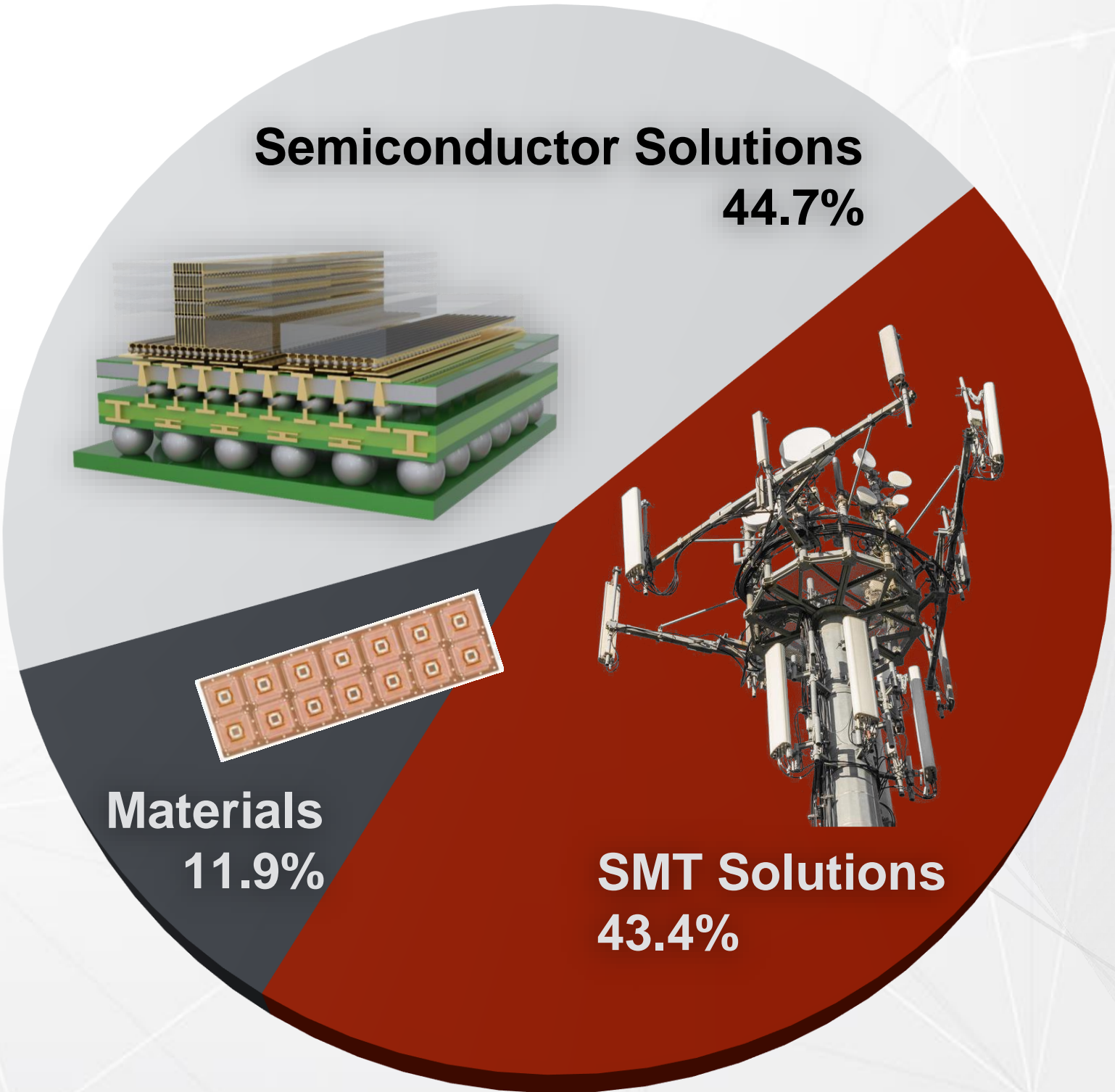
AWARDS /

Forbes Asia
— 2019 —
BEST OVER
A BILLION



The World's Technology & Market Leader


Q1 2020 Group Revenue:
USD 434m




ASMPT'S Major Facilities Around The World

OVERVIEW /







>2,000
Global R&D staff



>1,400
Patents on leading edge technologies



10
R&D centres worldwide



12
Manufacturing facilities

Three Business Segments With Leading Market Positions

SEMICONDUCTOR
SOLUTIONS¹
**#1 in Assembly
& Packaging
Equipment Market**

Since 2002

2019 Worldwide
PAE Market Share:

~29%

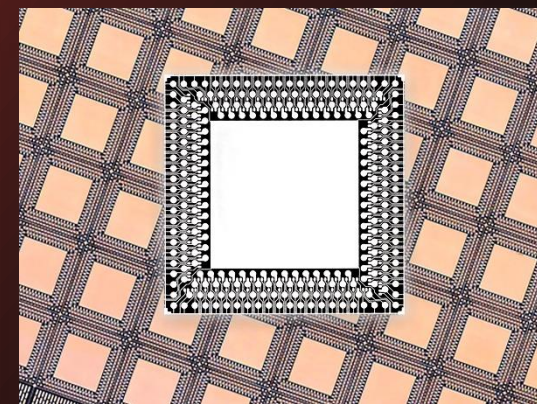


SMT SOLUTIONS

**#2 in SMT
Equipment Market**

2019 Worldwide
SMT Market Share:

~22%



MATERIALS

**#3 in Leadframe
Market**

2018 Worldwide
Leadframe Market Share:

~9%

¹FORMERLY BACKEND EQUIPMENT SOLUTIONS

2020 Q1 Highlights

Q1 2020 Billings

	USD	QoQ	YoY
Group	434m	-24.0%	-7.6%
Semi Solutions Segment	194m	-25.3%	-1.6%
Materials Segment	52m	-22.3%	+1.3%
SMT Solutions Segment	188m	-23.1%	-15.1%

Group

- Higher end of guidance

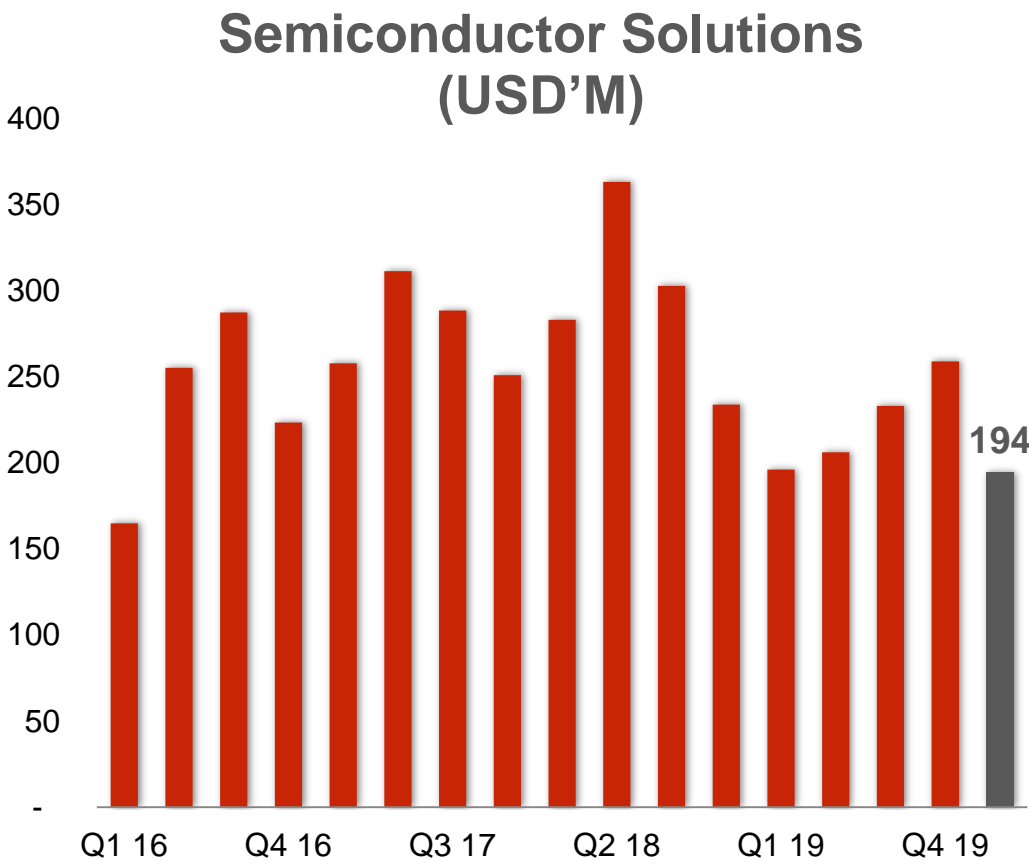
SEMI

- AP a key driver for Q1 20
 - AP > CIS revenue
- AP + CIS contributed close to 50% SEMI Revenue

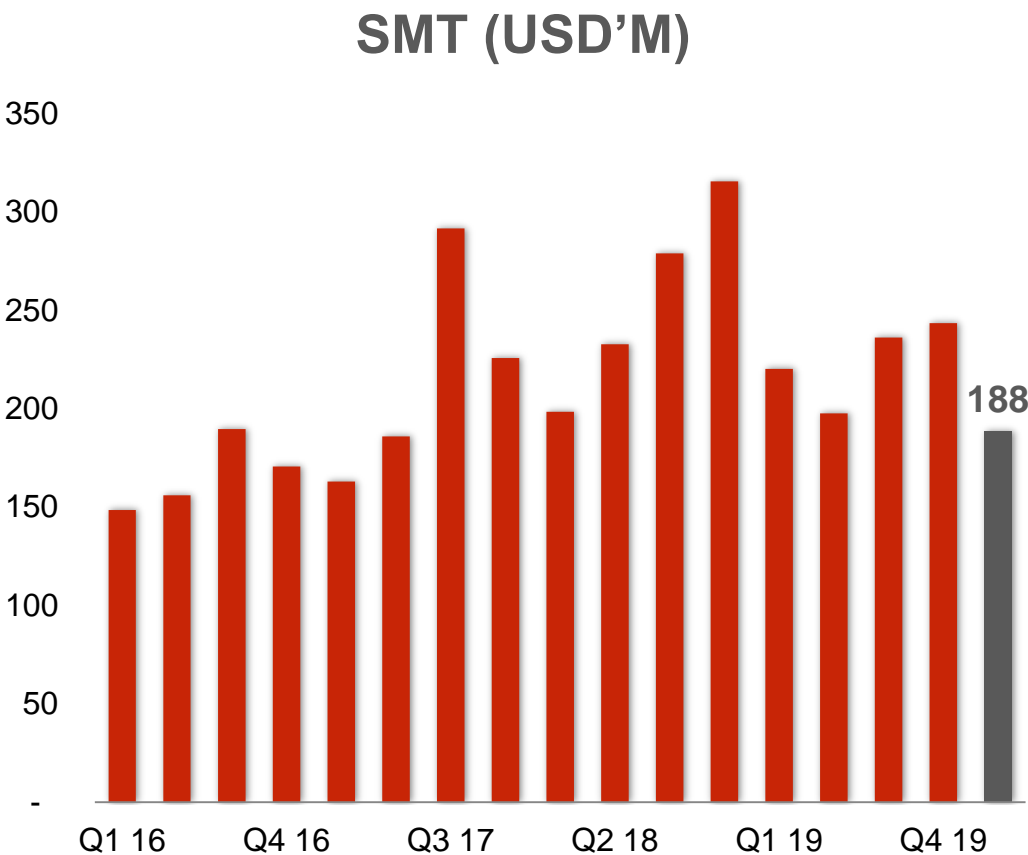
SMT

- Driven by 5G + SiP

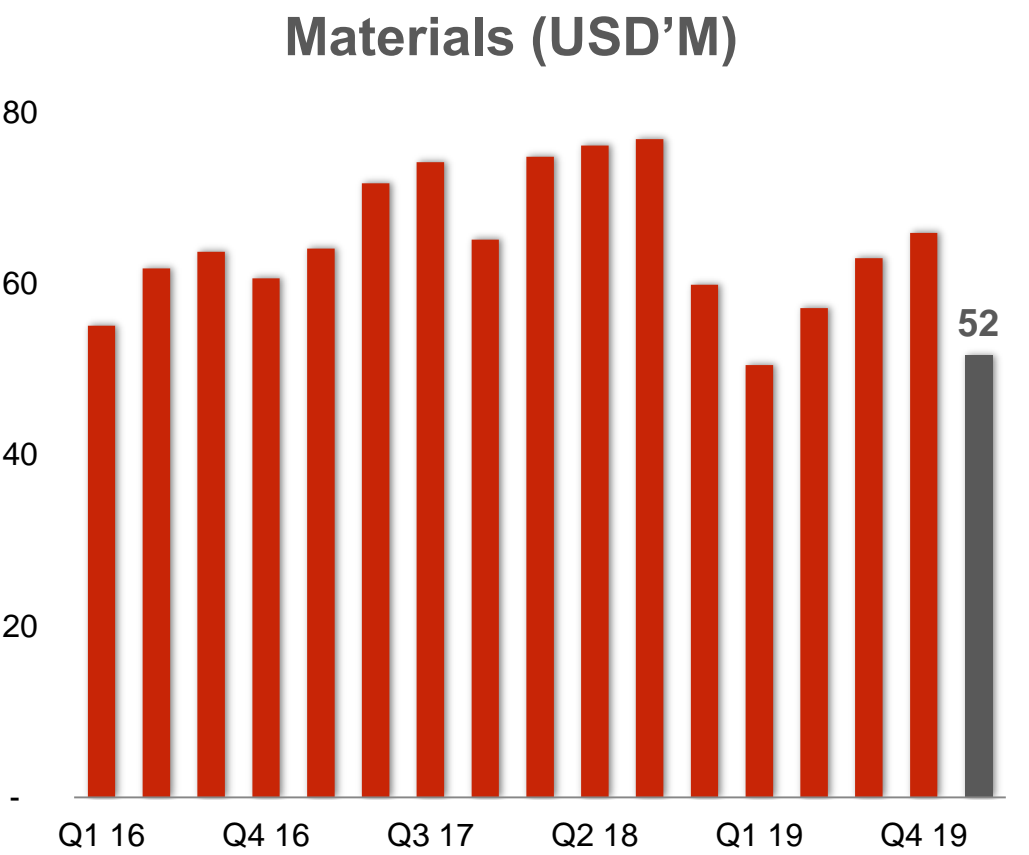
QoQ Growth:
-25.3%



QoQ Growth:
-23.1%



QoQ Growth:
-22.3%



Strong Q1 2020 Group Bookings

Q1 2020	USD	QoQ	YoY
Group	669m	+50.2%	+45.3%
Semi Solutions Segment	310m	+73.3%	+39.0%
Materials Segment	89m	+26.9%	+93.4%
SMT Solutions Segment	270m	+37.6%	+41.2%

Group

- 2nd highest ever Q1 bookings

SEMI

- Strong demand for traditional die/wire bonders
- Key driver
 - China localization
 - Advanced Packaging
 - General lighting
- Relatively weaker CIS demand due to softer smartphone market (COVID-19)

SMT

- Strong demand for 5G infrastructure and SiP
- High booking level similar to Q1 2018

Materials

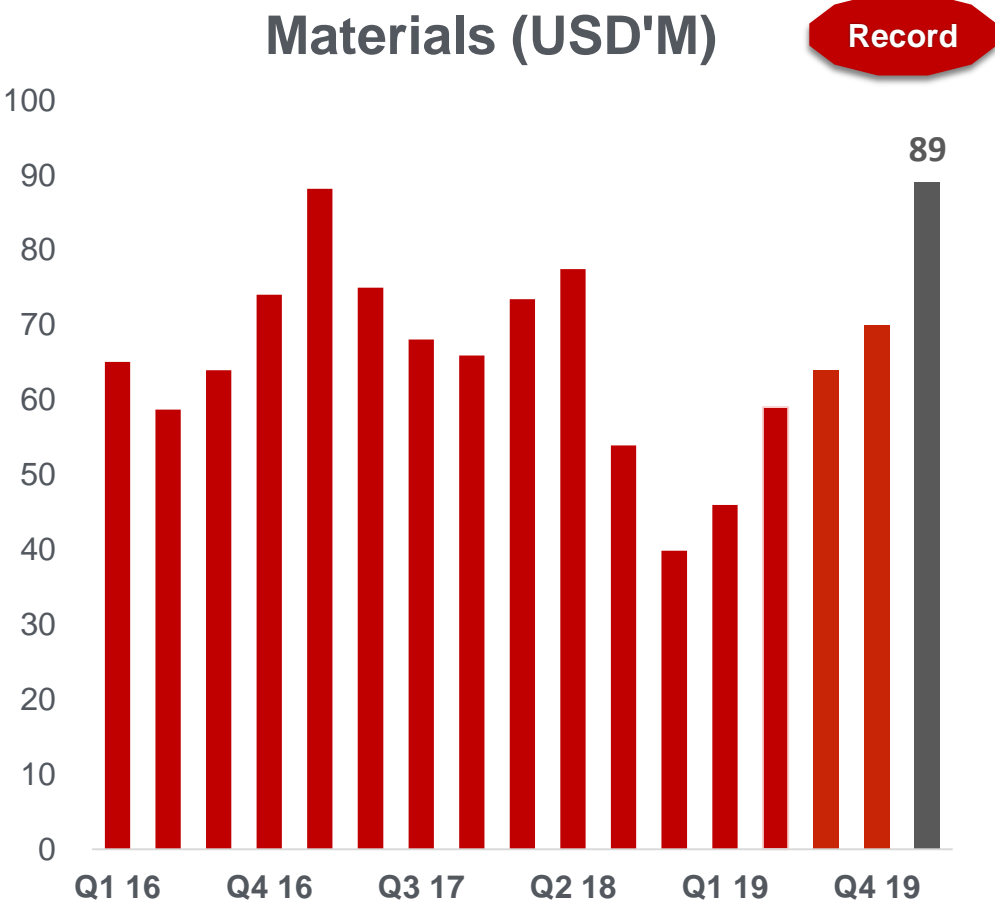
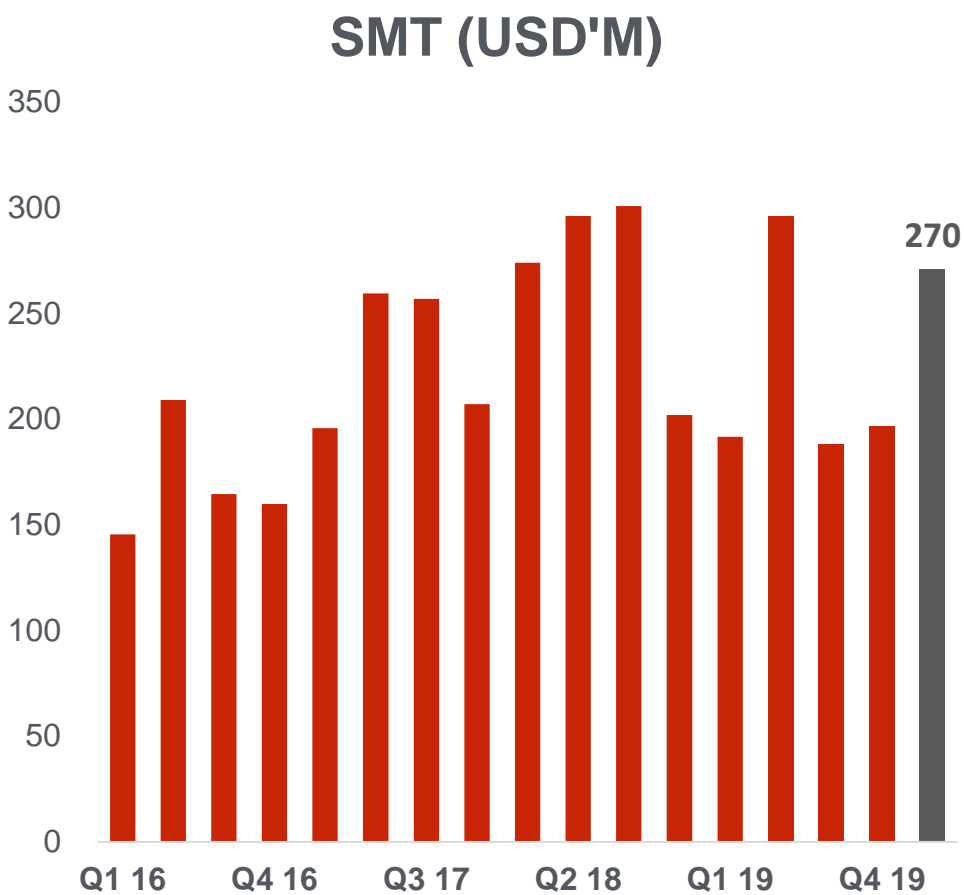
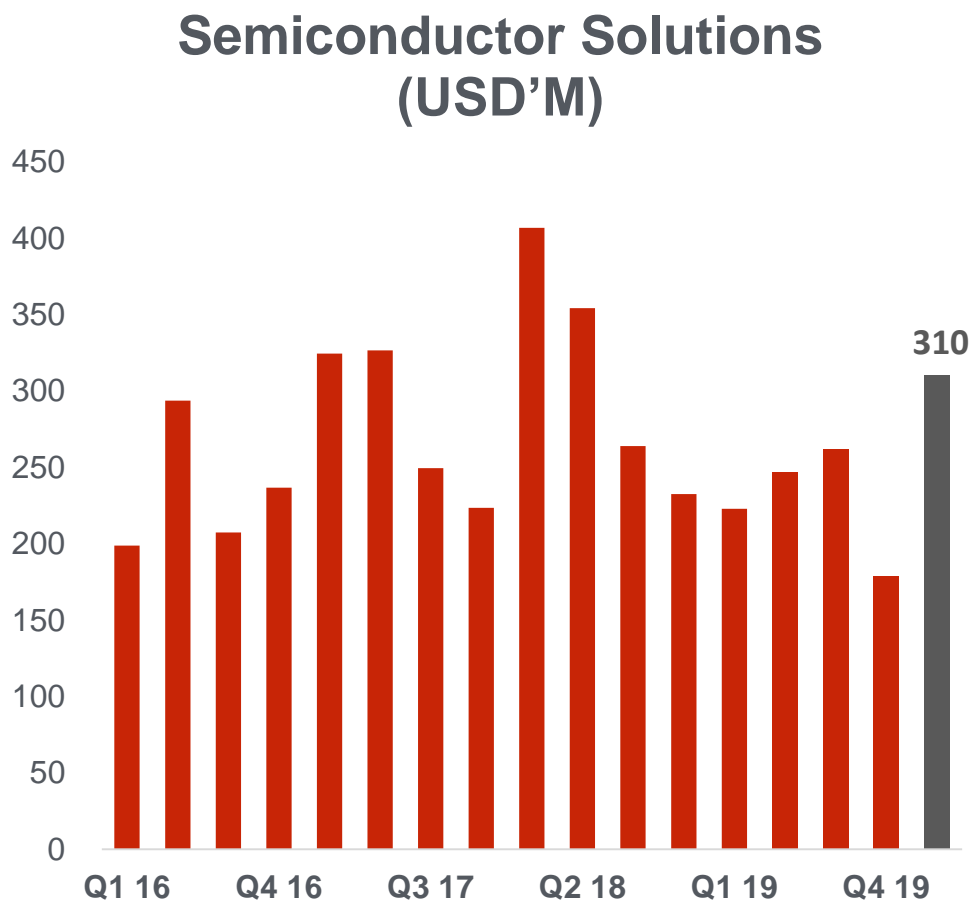
- 5th Consecutive QoQ growth
- Record high booking

QoQ Growth Across All Business Segments

QoQ Growth:
+73.3%

QoQ Growth:
+37.6%

QoQ Growth:
+26.9%



Q1 2020 Group GM & Profitability

Gross Margin	Gross Margin	QoQ	YoY
Group	33.5%	-125 bps	-37 bps
Semi Solutions Segment	41.3%	+45 bps	+202 bps
Materials Segment	8.5%	+7 bps	-188 bps
SMT Solutions Segment	32.4%	-312 bps	-214 bps
Group Billing (USD)	434m	-24.0%	-7.6%
Operating Profit (HKD)	145m	-65.4%	-39.3%
Net Profit (HKD)	25m	-88.6%	-76.6%

Group

- Net profit of HK\$25m – beats guidance for a loss this quarter
- Group GM ▼ mainly due to SMT's volume and geographical mix

SEMI

- GM increased QoQ and YoY due to product mix

SMT

- GM declined largely due to volume and geographical mix

Key Highlights:

Semiconductor Solutions Segment

- Demand for traditional die/wire bonders contributed to strong booking performance
- China localization effect and general lighting demand contributed to strong bookings for IC/Discrete and Optoelectronics
- Advanced Packaging continued to be strong
- AP + CIS contributed to close to 50% SEMI revenue; AP revenue contribution exceeded CIS in Q1 20
- Relatively weaker orders for CIS due to anticipated softness in smartphone market brought about by COVID-19

**YoY Bookings Growth:
+39.0%**



**YoY Bookings Growth:
+41.2%**

Key Highlights:

SMT Segment

- High booking level similar to Q1 2018 due to strong demand for
 - 5G infrastructure
 - System-in-Package (“SiP”)
- Slow down in Automotive continued

Key Highlights:

Materials Segment

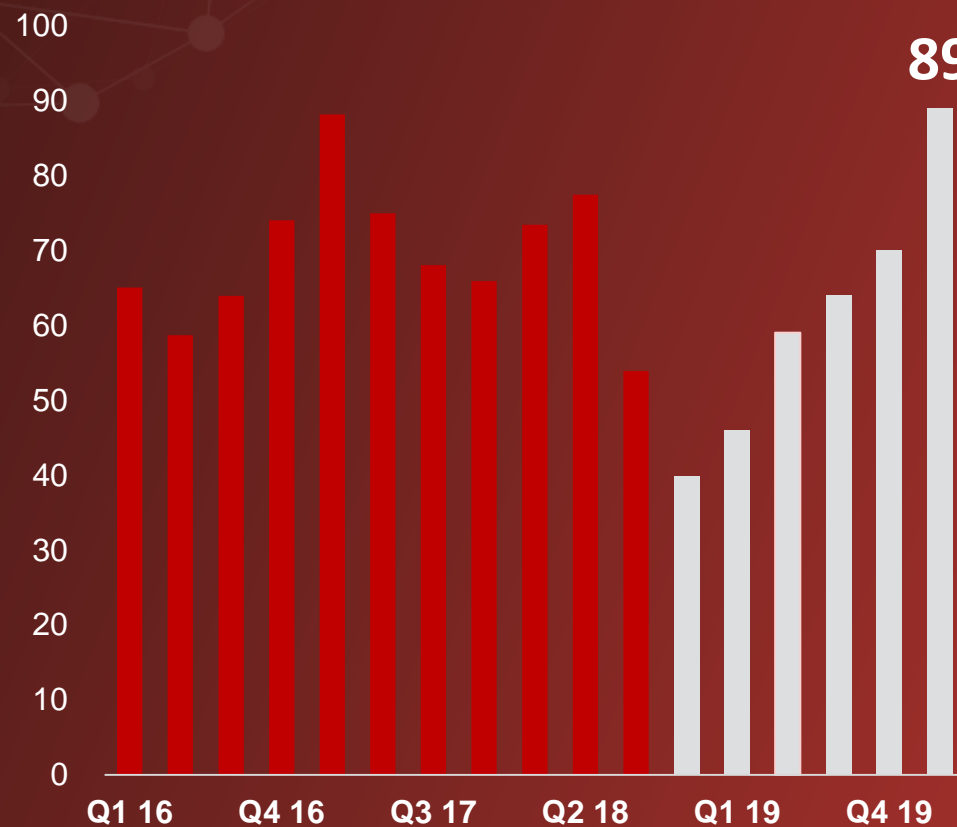
- Consecutive 5 quarters of Quarterly Bookings growth
 - Overwhelming indicator of market recovery; COVID-19 outbreak introduces uncertainty
- Profit improved by 51.3% YoY and 61.4% QoQ in absence of the recently discontinued MIS business
- GM and profitability expected to improve due to shifting of Leadframe operations from Singapore to Malaysia – completion expected Mid-2021

YoY Bookings Growth:
+93.4%

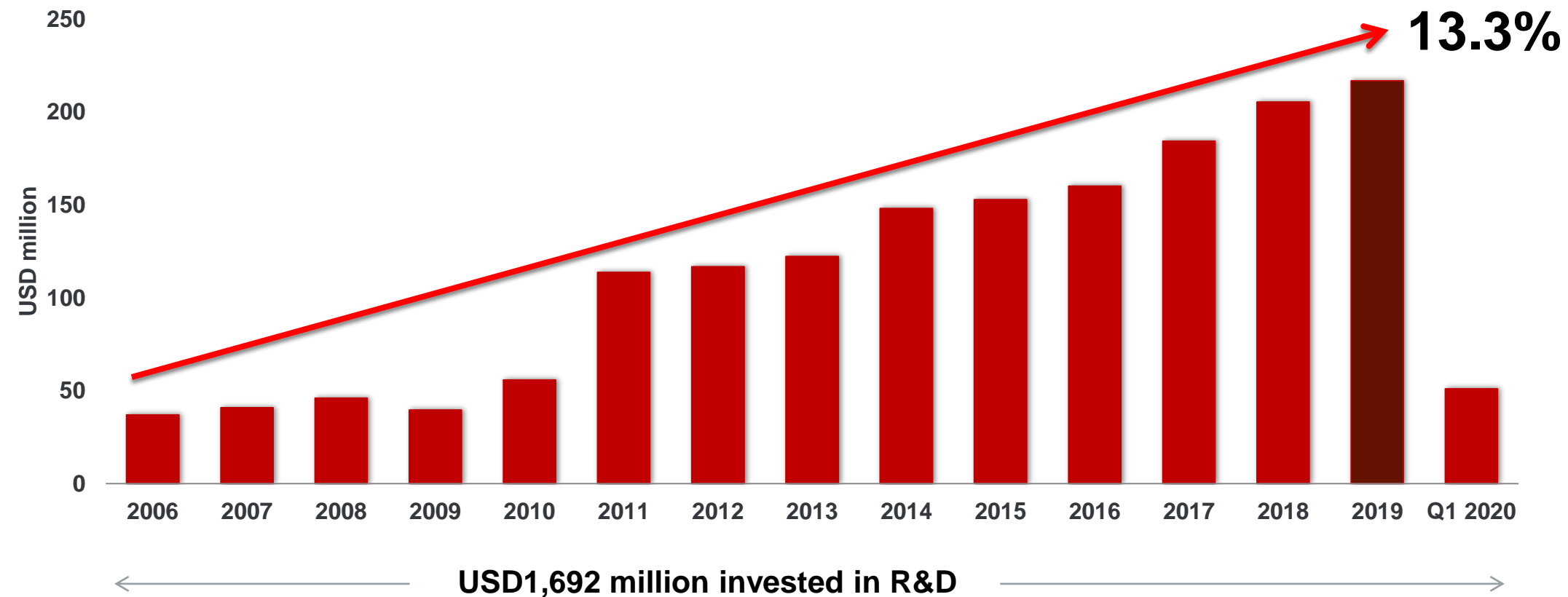
Materials (USD'M)

Record

89



R&D Commitment Makes Us a Preferred Partner of Choice

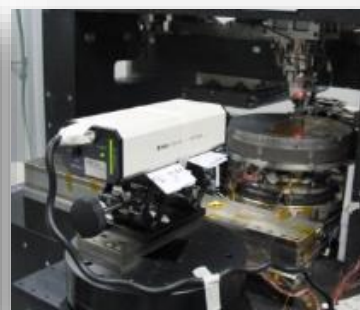


Q1 2020 R&D expenditure

- US\$ 51 million
- 13.3% of Equipment Sales



Package Interconnection



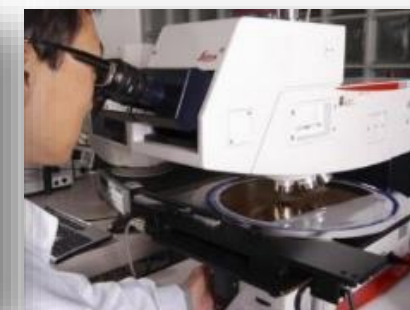
Optics precision engineering



Vibration control



Laser dicing & grooving

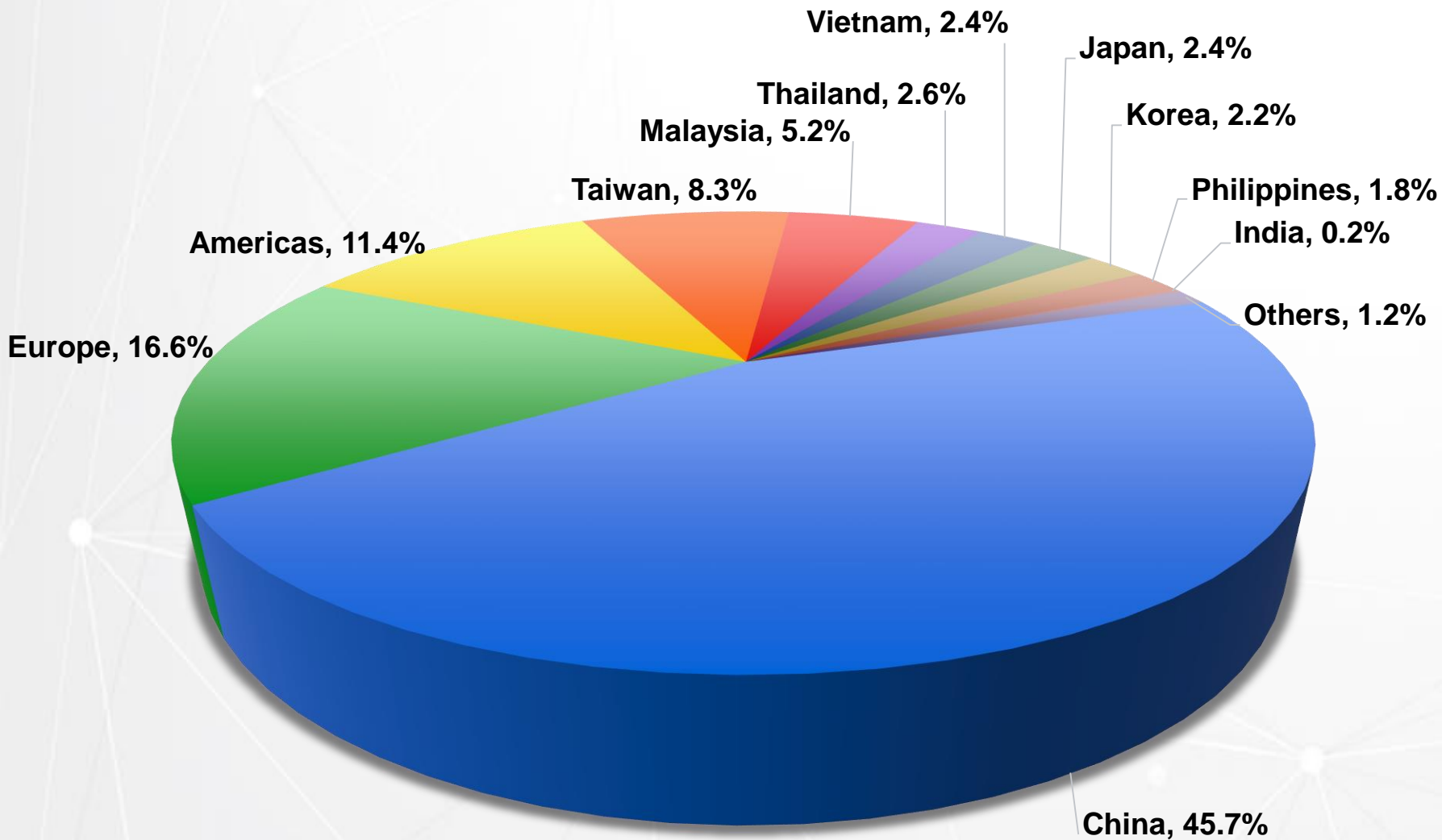


SMT



An Extensive Customer Base

Q1 2020 Geographical Distribution of Revenue

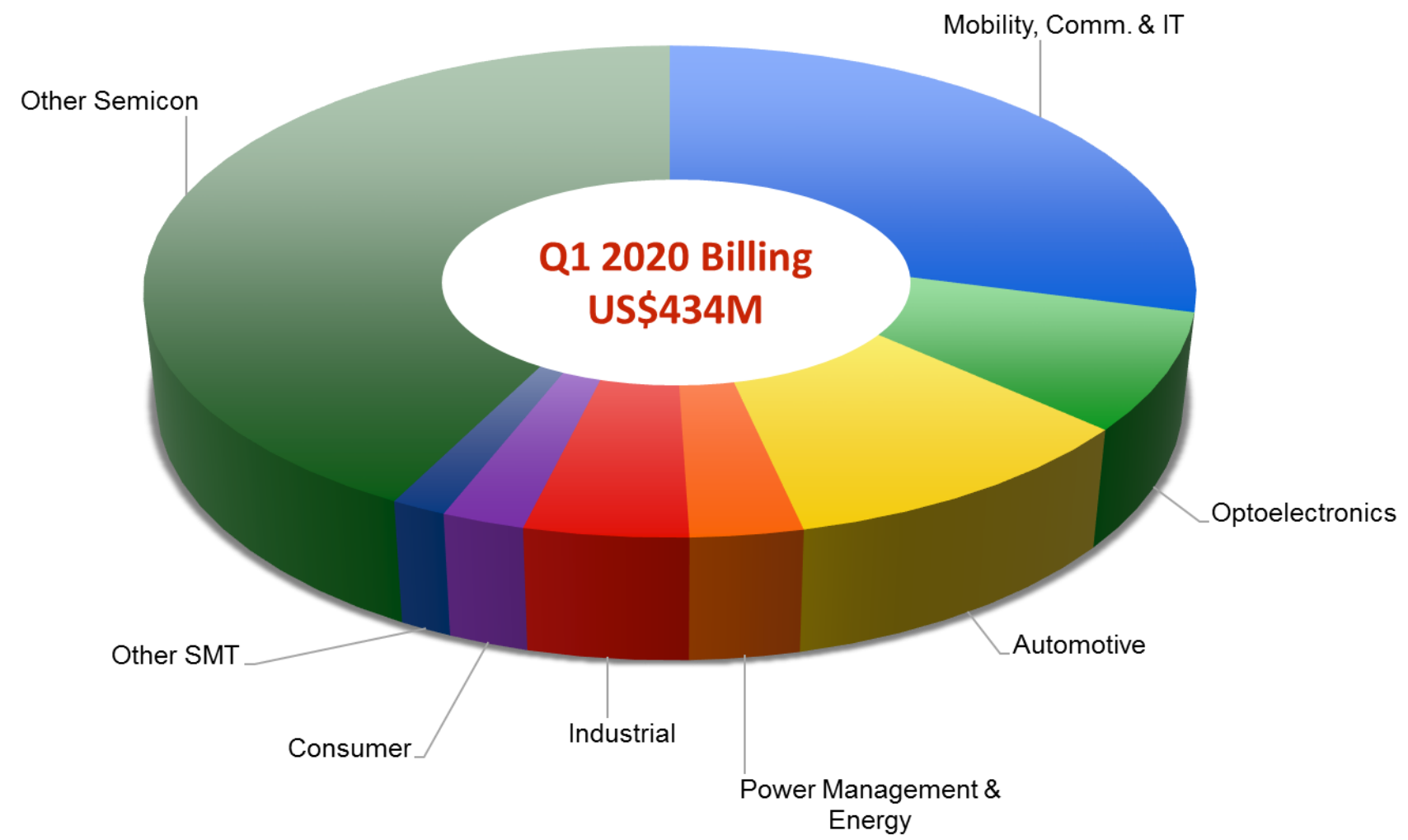


China Leads Market Recovery

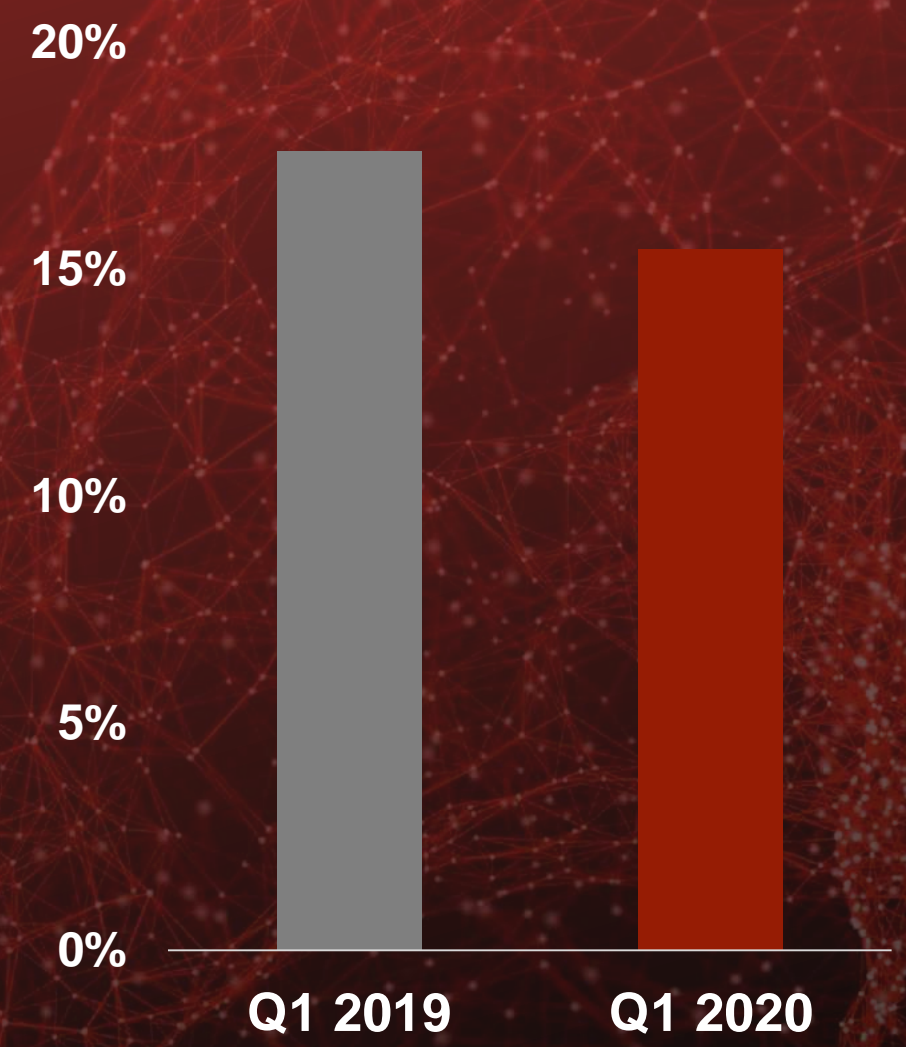
- No single customer accounted for more than 10% of Group revenue
- Top 5 customers accounted for 15.4% of Group's Q1 2020 revenue
- Top 20 customers include:
 - World's leading Telecommunication and Information Technology provider
 - Leading High-Density Substrate makers
 - World's leading IDMs
 - Tier 1 OSATs, major OSATs in China
 - Major camera module makers
 - Top EMS providers
 - Leading automotive component suppliers
- Among Top 20 customers of Group:
 - 7 from SMT Solutions segment
 - 6 from both Semi Solutions & SMT Solutions segment

Q1 2020 Revenue Breakdown by Application Markets

Q1 2020 Billing by Market Application



Top 5 Customers Revenue Contribution

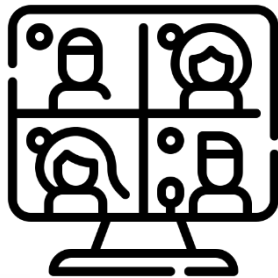


More Resilient in a Downturn with Multiple Application Markets Strategy

New Lifestyle Norms **Fast-tracking Digitalization**



'Work from Home' Initiatives by Companies Worldwide



“Zoom, Microsoft Teams usage are rocketing”
Marketwatch, April 2020



Home-based Learning adopted by schools



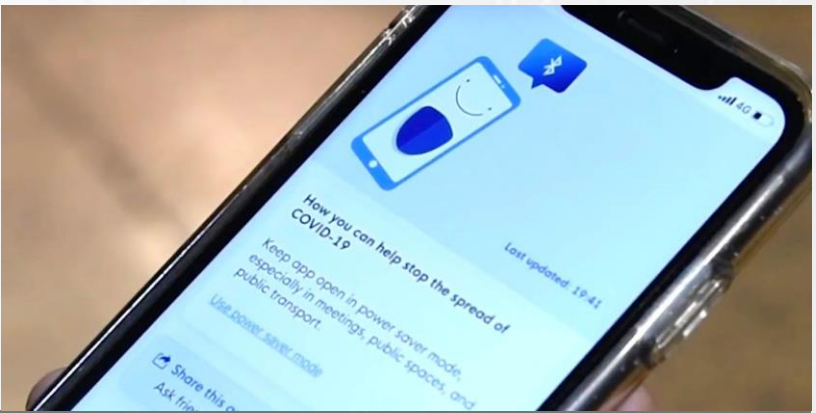
Online “Live” Fitness Classes



“Apple and Google partner on COVID-19 contact tracing technology”
Apple, Google, April 2020

“First-Quarter Demand Picked Up on Laptop Orders”

Intel



Harnessing Technology in Contact Tracing

Data-Centric Era will spur Semiconductor Demand



Collect

Camera, 3D Sensing,
Industry IoT, Sensor,
LIDAR



Transmit

5G, WiFi, LiFi



Store

Big Data Centre,
Cloud Computing,
Memory



Analyse

AI, TPU, Data
Analytics, HPC



Visualise

AR, VR, Micro
LED, Mini LED

ASMP's Enabling
Solutions

- CMOS Imaging Sensors
- Active Alignment
- Precision Die Attach

- Silicon Photonics
- RF Filters
- Wire Bonding
- SAW Filters
- BAW Filters
- SMT Solutions
- PVD

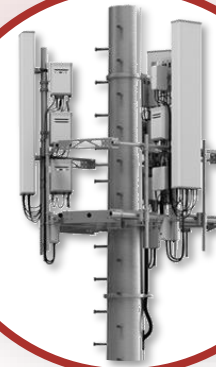
- Silicon Photonics
- TCB
- Wire Bonding
- PLFO
- Laser Dicing

- WLFO
- PLFO
- Pick & Place
- Laser Grooving
- TCB
- PVD/ECD
- Precision Die Attach
- Heterogeneous Integration

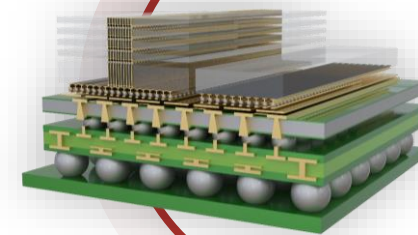
- High Precision Die Attach
- Mini/Micro LED Displays



China Supply Chain Localization



5G



**Advanced
Packaging**



Optoelectronics

Q1 2020 Growth Drivers For ASMPT

5G Will Transform the World Beyond Our Imagination



5G

Infrastructure

**2019-2025: 25-30mil
New 5G
Base Stations**
Source: Topology Research Institute 2019

Terminal

**2023: 417mil
New 5G
Handsets**
Source: IDC, 2019


**Big Data
Cloud Servers**


Smart Consumer


**“Power” Up
All Industries**


**50 MEMS & Sensors
per car
Automotive**

Source: Bosch, 2019

ASMPT Solutions for 5G:


**Photonics
Solutions**


IC & Discrete Solutions


**Image Sensor
Solutions**


**Advanced
Packaging**


SMT Solutions


Power Solutions


Wafer Separation

Broad-Based Applications In CIS Market

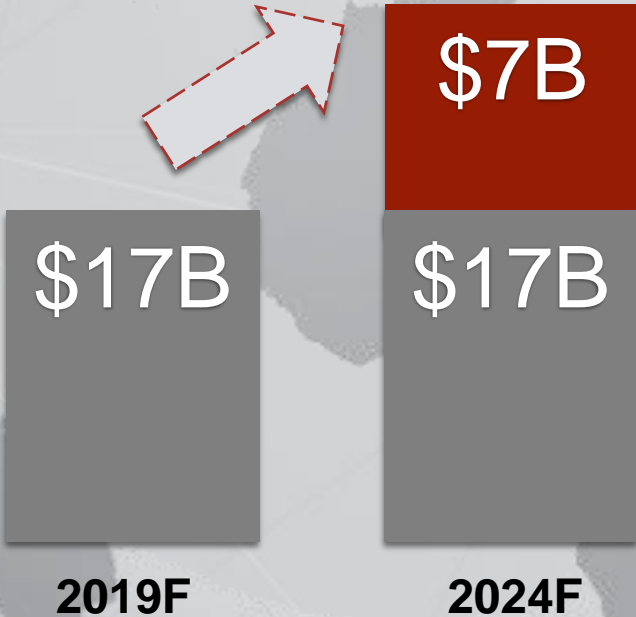
Worldwide CIS Unit Shipment CAGR
(2020 – 2023)

Source: Yole, Sep 2019

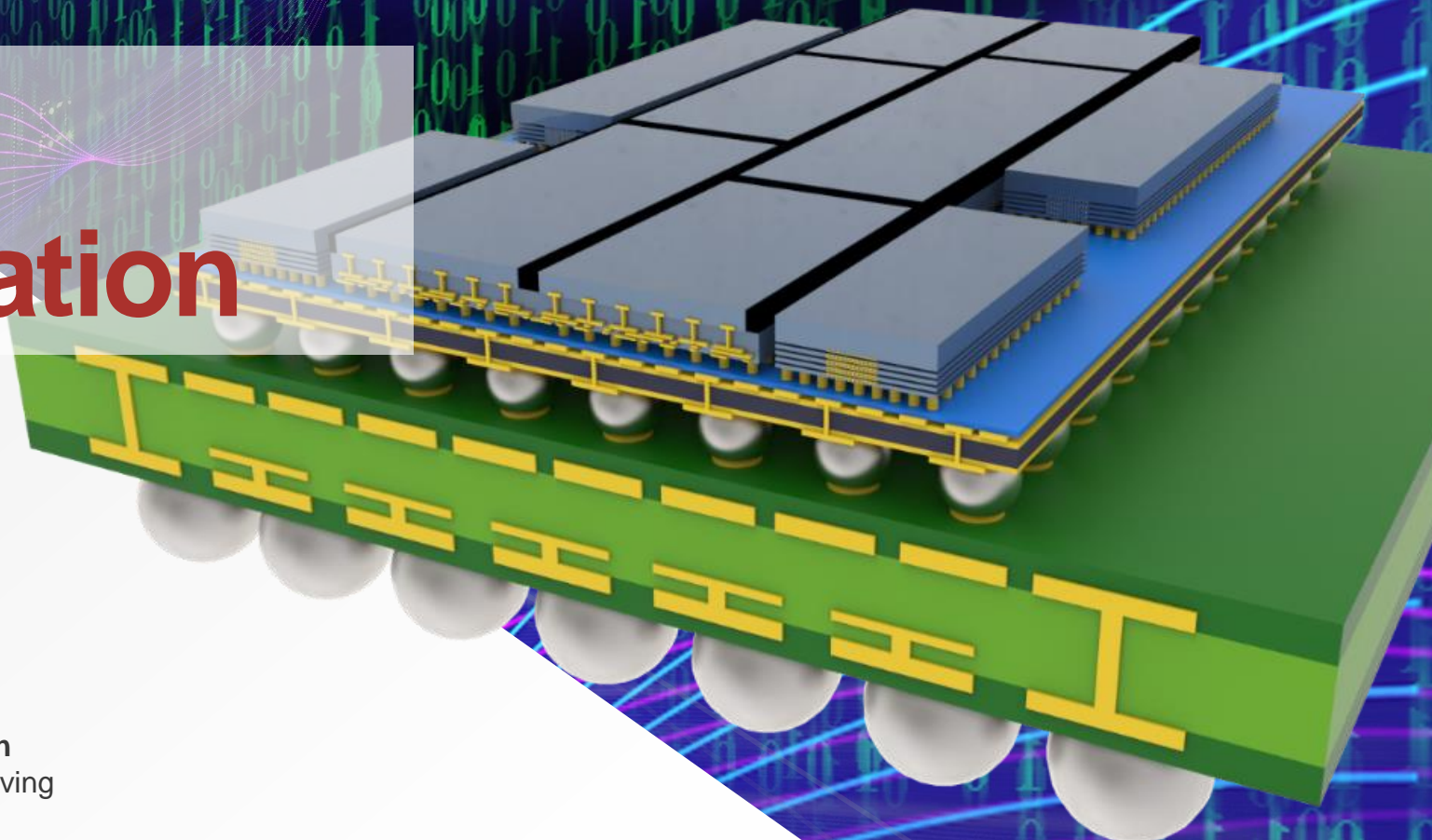
13%

CIS Market to Reach US\$24B by 2024

Source: Yole, Q3 2019



Advanced Packaging Enables Heterogeneous Integration



SIPLACE CA
Die Attach & SMT
Wafer & Panel Recon
IPD tool



NEXX
PVD | ECD
Bumping, TSV & RDL



LASER 1205
Laser Separation
Wafer Dicing & Grooving



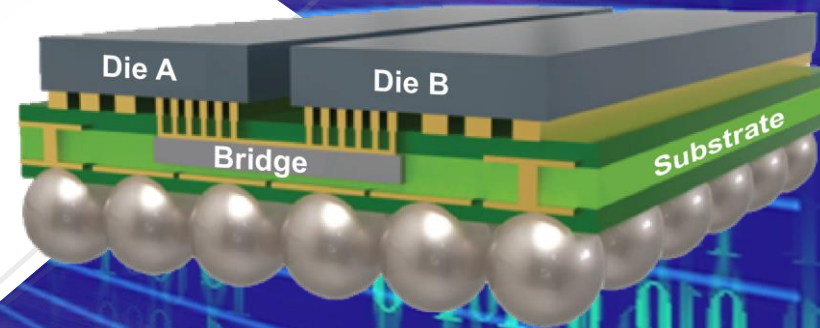
NUCLEUS XPM
HBM Bonder



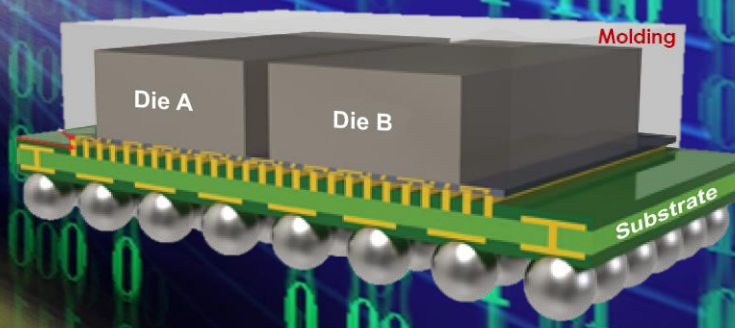
NUCLEUS
Pick & Place
Wafer & Panel Level



ORCAS
Compression mold
Wafer & Panel Level



FIREBIRD
TCB, FLI



End Applications:

DATACENTERS
for HPC, Machine Learning



IoT ERA
Smart Wearables & Smart Machines (Factories)



AUTOMOTIVE
Sensors, Camera, Body Electronics, Safety Systems, Infotainment



GPU
for VR/AR & AI



Future Growth Drivers for OPTO Business

MiniLED

Medium to Large
RGB / BLU Display

Market Size CAGR (2019 – 2025)

~ 35%

Market Size CAGR (2019 – 2025)

~ 131%

MicroLED

Small Gadget &
Transparent Display

Fast Growing Applications

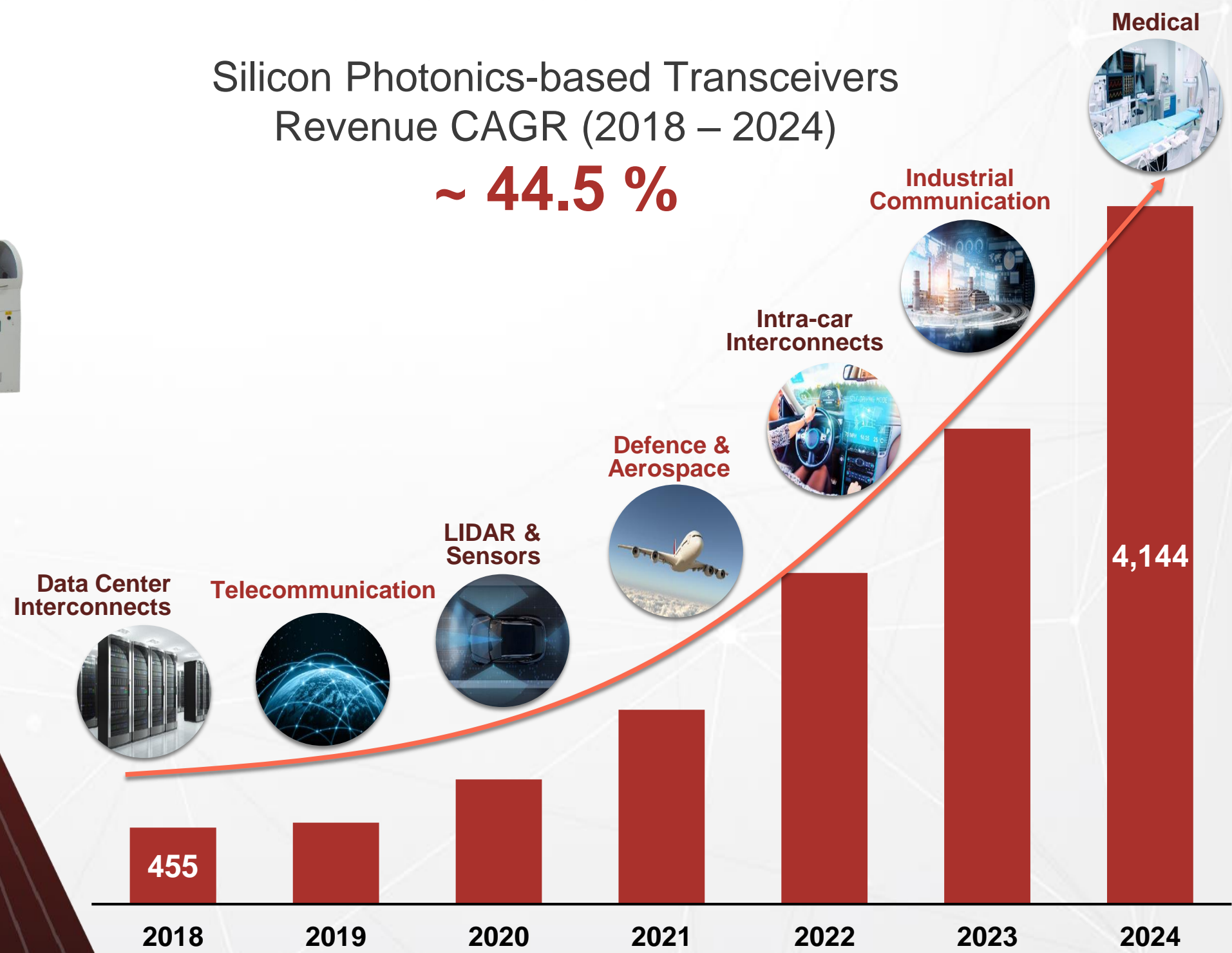
Source: LEDInside, Sep 2019



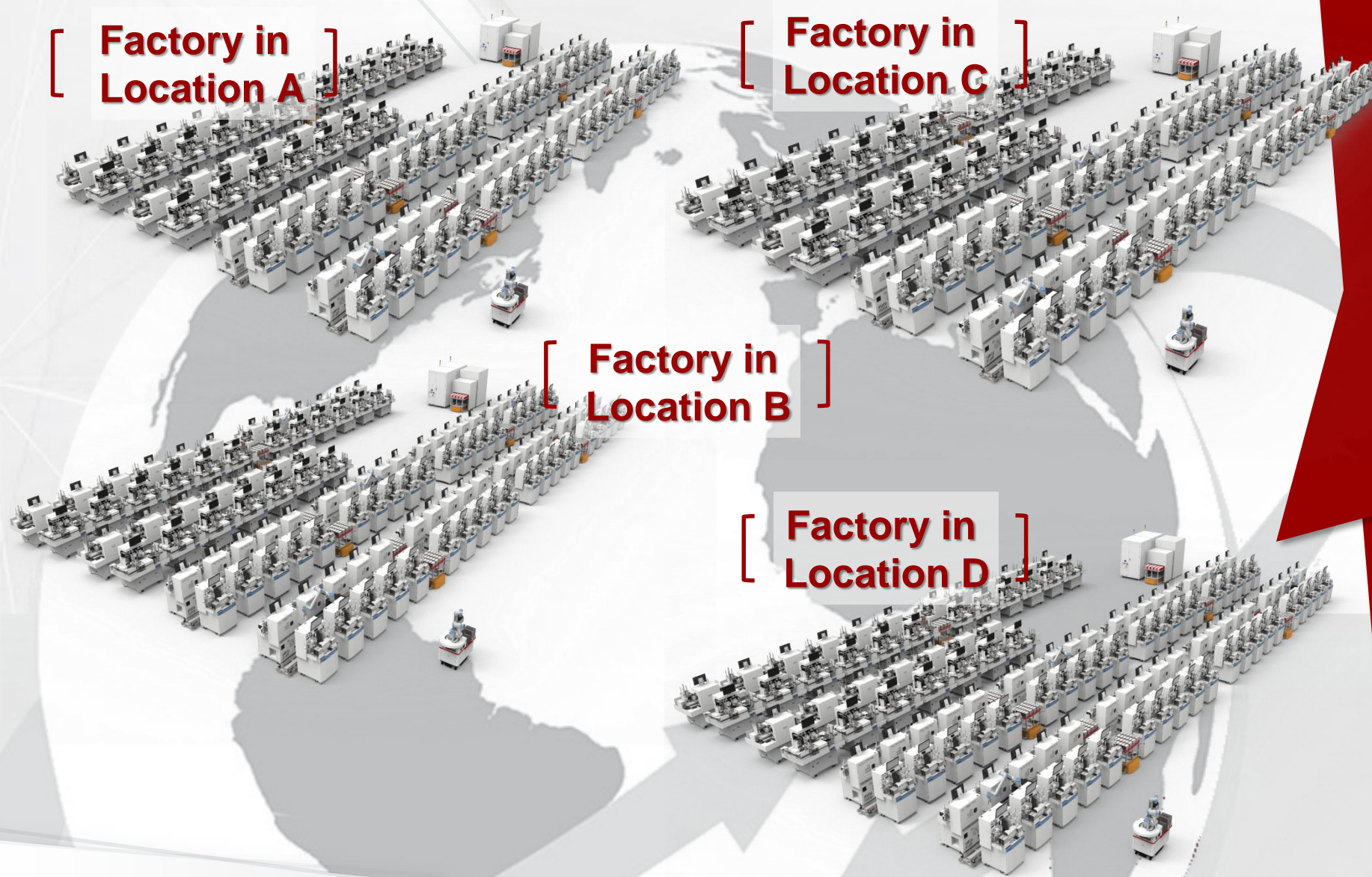
Booming Applications in Photonics Market

Silicon Photonics-based Transceivers
Revenue CAGR (2018 – 2024)

~ 44.5 %



IIoT & Smart Manufacturing Powered Up by 5G Network



Industrial IoT
~ 24%

CAGR (2019 – 2023)

Source: Marketwatch,
Sep 2019



How will 'Smart Cars' Drive ASMP's Growth?



Power Management

Battery Technology for thermal management
Thermal management (e.g. Ag Sintering) will play important role



5G to Cloud Connectivity

Vehicle-to-X (Vehicle, Infrastructure, Network, Devices) communications
Enable "V2X" communications



Sensors

Image, LIDAR, Radar
The eyes and ears to gather information from the Road



Entertainment Platform

Television, Mobile devices, VR/AR, Gaming, etc.
Frees up driver's attention on road for entertainment

Outlook

COVID-19 Update

OUTLOOK /

SITUATION UPDATE

- ~100% of employees in China plants have returned to work
- Some production capacity lost in China plants; Working towards recovering big portion of lost capacity through productivity gain and overtime
- Group is grateful to suppliers who had supported us
- While Singapore and Malaysian plants may be affected, impact is cushioned with diversified manufacturing base
- Minimal impact to plant operations in USA and Europe
- Strong local support teams to serve our customers to ensure smooth operations of our customers

Q2 Group Bookings

- Double digit percent decline QoQ due to COVID-19 impact
- Strong momentum from Materials Segment in April month to date; Demand momentum for traditional tools in SEMI Solutions Segment not as strong

Q2 Group Billings

- US\$500m – US\$580m
- Demand from information technology and datacenter related applications driven by increased telecommuting and home-based working activities
- Strong Q1 Bookings expected to be delivered over several quarters due to production lead time as well as some delivery push-outs to Q3

Q2 Group Gross Margin

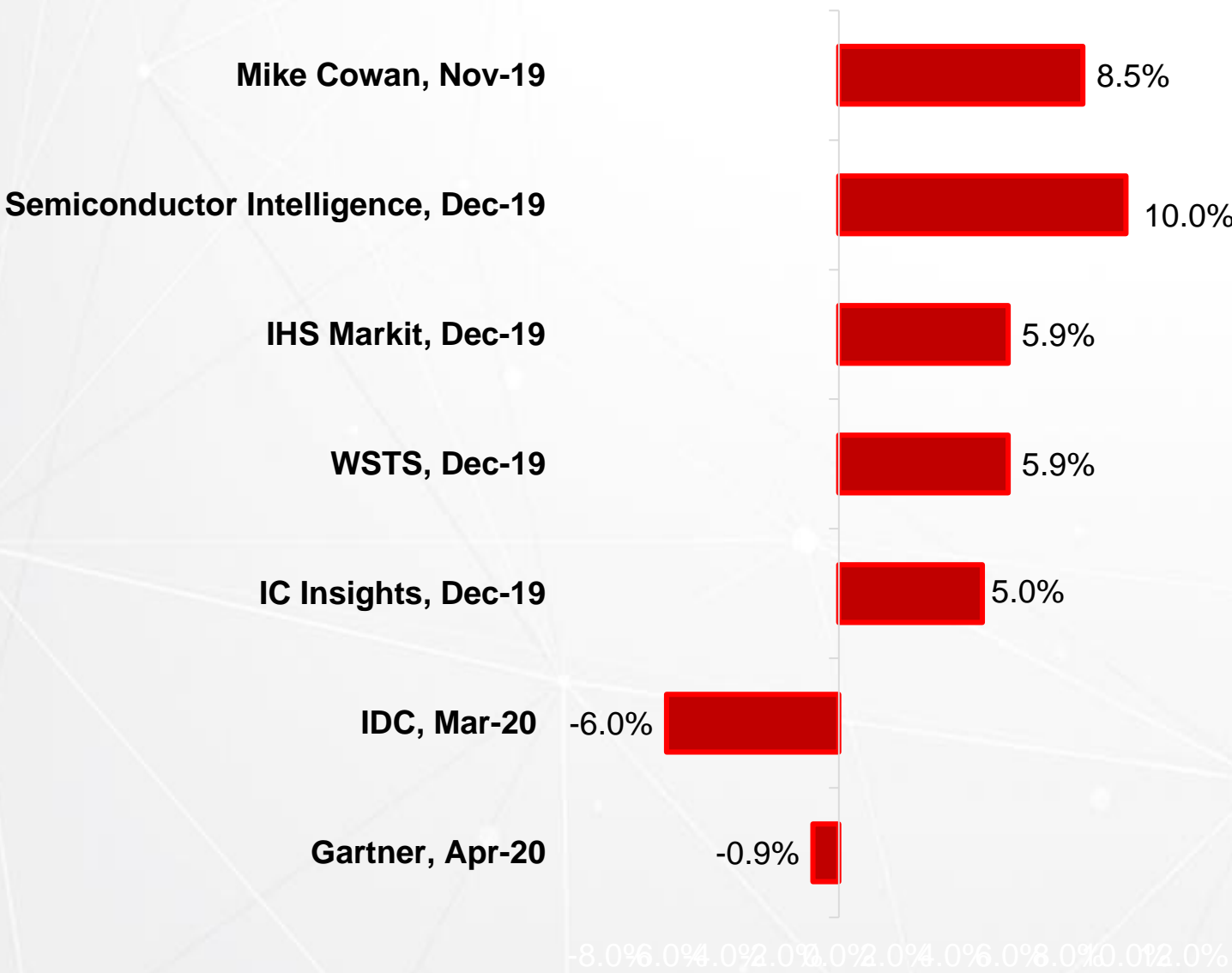
- 34.5% - 36.5%

A Myriad of Growth Drivers for 2020 & Beyond – *with acceleration for Digitalization*

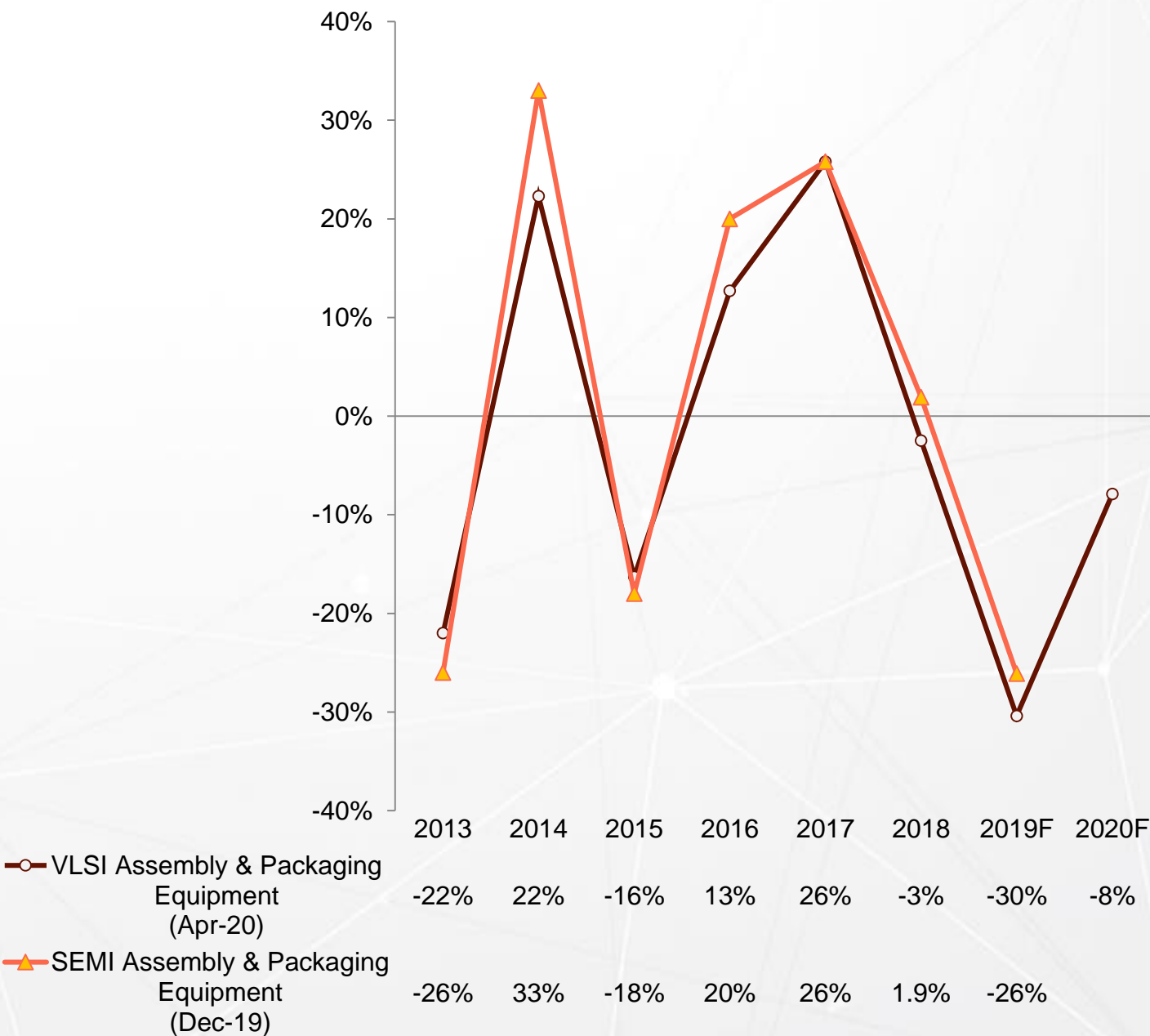
- 5G infrastructure and handsets: remains multi-year / multi-country driver
- Strong pick-up in demand from Chinese manufacturers to localize supply chains
- “New Normal” fast-tracking digitalization with worldwide home-based learning and remote working initiatives
- New market opportunities for Advanced Packaging, Silicon Photonics, Industrial IOT, mini and micro LED solutions
- ASMPT is well positioned to take advantage of this unique window of opportunity

Industry Growth Forecast (2020)

Semiconductor Industry



Forecast Global Assembly & Packaging Equipment Market



Recent Awards & Recognition

Latest

				
10 BEST Segment	Rank	10 BEST CHIP MAKING EQUIPMENT SUPPLIERS OF 2019	Rating	Stars
L A R G E	1	TERADYNE	9.44	★★★★★
	2	ADVANTEST	9.23	★★★★★
	3	ASML	9.18	★★★★★
	4	ASM  Pacific Technology	8.79	★★★★★
	5	 KLA Keep Looking Ahead	8.03	★★★★★
	6	 TEL TOKYO ELECTRON	7.83	★★★★★
	7	 KE KOKUSAI ELECTRIC	7.75	★★★★★
	8	 Lam RESEARCH	7.61	★★★★★
	9	 APPLIED MATERIALS	7.36	★★★★
	10	Hitachi High-Tech	7.29	★★★★
F O C U S E D	1	 Plasma Therm	9.39	★★★★★
	2	 AMEC	9.01	★★★★★
	3	 FORMFACTOR™	8.89	★★★★★
	4	 EVG	8.51	★★★★★
	5	 SPTS An Orbotech Company	7.46	★★★★
	6	 Cohu	7.09	★★★★

Source: VLSresearch
css 10BEST v19.05

		WHAT THE BEST SUPPLIERS OF 2019 ARE BEST AT	
ADVANTEST	<ul style="list-style-type: none"> Partnering Technical Leadership 	 AMEC	<ul style="list-style-type: none"> Partnering Commitment
 APPLIED MATERIALS	<ul style="list-style-type: none"> Technical Leadership Software 	ASM  Pacific Technology	<ul style="list-style-type: none"> Partnering Trust in Supplier
ASML	<ul style="list-style-type: none"> Technical Leadership Partnering 	 Cohu	<ul style="list-style-type: none"> Trust in Supplier Partnering
 EVG	<ul style="list-style-type: none"> Partnering Recommend Supplier 	 FORMFACTOR™	<ul style="list-style-type: none"> Field Engineering Support Technical Leadership
Hitachi High-Tech	<ul style="list-style-type: none"> Uptime Product Performance 	 JAPAN ELECTRONIC MATERIALS	<ul style="list-style-type: none"> Product Performance Support After Sales
 KLA Keep Looking Ahead	<ul style="list-style-type: none"> Technical Leadership Application Support 	 KE KOKUSAI ELECTRIC	<ul style="list-style-type: none"> Partnering Support After Sales
 Lam RESEARCH	<ul style="list-style-type: none"> Field Engineering Support Recommend Supplier 	 Nidec SVTCL	<ul style="list-style-type: none"> Commitment Support After Sales
 Nikon	<ul style="list-style-type: none"> Partnering Trust in Supplier 	 Plasma Therm	<ul style="list-style-type: none"> Recommend Supplier Support After Sales
 SPTS An Orbotech Company	<ul style="list-style-type: none"> Recommend Supplier Field Engineering Support 	 TECHNOPROBE Wafer Probing Technologies	<ul style="list-style-type: none"> Commitment Partnering and Recommend Supplier
TERADYNE	<ul style="list-style-type: none"> Recommend Supplier Technical Leadership 	 TEL TOKYO ELECTRON	<ul style="list-style-type: none"> Technical Leadership Uptime

Source: VLSresearch Doc: css_THEBEST_v19.05

Q1 2020 Financial Highlights

Q1 2020 Group Bookings

**QoQ Growth:
+50.2%**

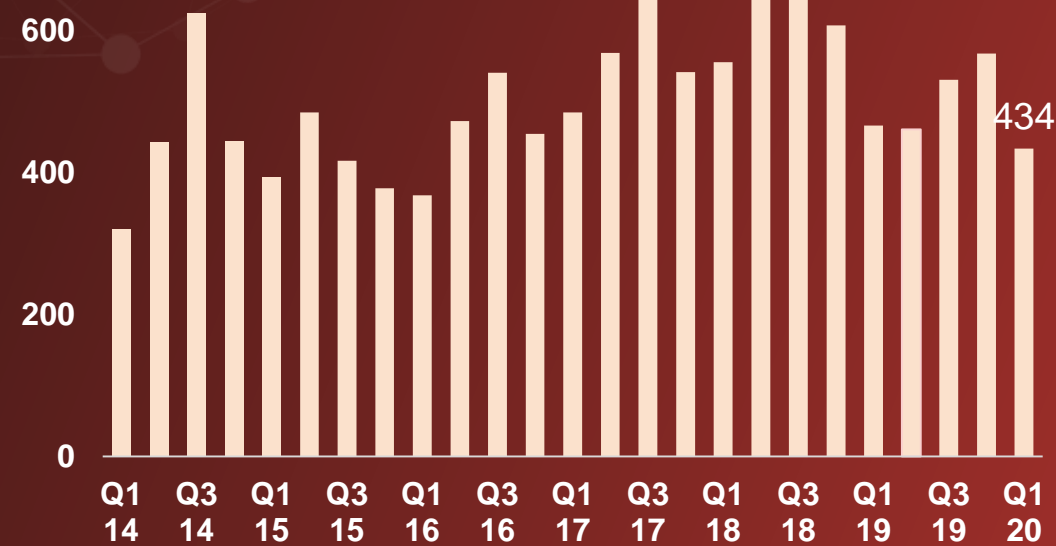


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Semi Solutions Segment	310m	+39.0%	+73.3%
Materials Segment	89m	+93.4%	+26.9%
SMT Solutions Segment	270m	+41.2%	+37.6%

Q1 2020 Group Billings

QoQ Growth:
-24.0%



**Quarterly Group Billings
(USD'M)**

Q1 2020 Billings

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Group	434m	-7.6%	-24.0%
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Q1 2020 Group Financial Highlights

FINANCIAL REVIEW /

		Q1 2020	
		QoQ	YoY
Bookings (USD)	669m	+50.2%	+45.3%
Revenue (USD)	434m	-24.0%	-7.6%
Gross Margin	33.5%	-125 bps	-37 bps
EBIT (HKD)	124m	-59.1%	-53.1%
Net Profit (HKD)	25m	-88.6%	-76.6%
Net Profit Margin	0.7%	-424 bps	-221 bps

Q1 2020 Segment Results – Semiconductor Solutions

		Q1 2020	
		QoQ	YoY
Bookings (USD)	310m	+73.3%	+39.0%
Billings (USD)	194m	-25.3%	-1.6%
Gross Margin	41.3%	+45 bps	+202 bps
Segment Profit (HKD)	85m	-52.6%	+59.8%
Segment Profit Margin	5.6%	-321 bps	+215 bps

Q1 2020 Segment Results – Materials

		Q1 2020	
		QoQ	YoY
Bookings (USD)	89m	+26.9%	+93.4%
Billings (USD)	52m	-22.3%	+1.3%
Gross Margin	8.5%	+7 bps	-188 bps
Segment Profit (HKD)	16m	+61.4%	+51.3%
Segment Profit Margin	3.9%	+205 bps	+130 bps

Q1 2020 Segment Results – SMT Solutions

		Q1 2020	
		QoQ	YoY
Bookings (USD)	270m	+37.6%	+41.2%
Billings (USD)	188m	-23.1%	-15.1%
Gross Margin	32.4%	-312 bps	-214 bps
Segment Profit (HKD)	126m	-54.6%	-40.8%
Segment Profit Margin	8.6%	-597 bps	-374 bps

ASM Pacific Technology

ENABLING THE DIGITAL WORLD

